



# PCB Launch Optimization Services

## Description:

The Amphenol CDI team is dedicated to ensuring the seamless integration of our CoreHC and other solderless precision connectors into your platform. We offer comprehensive support through simulation services that optimize your footprint based on your specific PCB stack-up, complemented by a suite of encrypted HFSS models for independent footprint analysis.

Recognizing that the PCB is crucial for connector performance, our process considers key factors such as signal transition dimensions, layer count, dielectric materials, and routing styles. By running detailed simulations, we help engineers achieve the best possible outcomes tailored to their target specifications and frequency requirements.

Once optimization is complete, our team collaborates closely with you to finalize the footprint layout. Given that the CoreHC connector may be unfamiliar to many layout engineers, we provide expert guidance throughout the design process, ensuring a smooth and effective implementation.

## Key Benefits:

- Custom-tuned footprint to your specific PCB stack-up
- Full S-Parameter and s2p output
- Xtalk-specific optimizations available
- Reduced layout workload for engineers

## What's Needed to get Started?

- Amphenol supplied *Optimization Checklist* returned completed
- Copy of the projects Stack-up

Mode	Frequency (MHz)	Loss (dB)	Return Loss (dB)	SWR	Efficiency (%)
TE <sub>10</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>20</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>30</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>40</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>50</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>60</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>70</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>80</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>90</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>100</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>110</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>120</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>130</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>140</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>150</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>160</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>170</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>180</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>190</sub>	1000	0.15	18.0	1.05	99.85
TE <sub>200</sub>	1000	0.15	18.0	1.05	99.85

## Deliverables:

- Footprint report outlining geometry specifics
- 3D step file of optimized pad-stack
- S2p file and S-parameters of optimized performance
- Additional post-implementation footprint reviews

